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(12) **United States Design Patent**  
**Chung**

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- (54) **HEAT SINK FOR MEMORY MODULES**
- (71) Applicant: **ESSENCORE Limited**, Hong Kong (HK)
- (72) Inventor: **Young Suk Chung**, Yongin-si (KR)
- (73) Assignee: **ESSENCORE Limited**, Hong Kong (HK)
- (\*\*) Term: **15 Years**
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- (51) **LOC (13) Cl.** ..... **13-03**
- (52) **U.S. Cl.**  
USPC ..... **D13/179**
- (58) **Field of Classification Search**  
USPC ..... D13/179; D14/435  
CPC ..... H01L 23/28; H01L 23/36; H01L 23/367;  
H01L 23/3672; H01L 23/3675; H01L  
23/3677; H01L 23/4093; H01L 23/467;  
G06F 1/20; H05K 7/2039; H05K 7/20509  
See application file for complete search history.

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*Primary Examiner* — Selina Sikder  
(74) *Attorney, Agent, or Firm* — Sughrue Mion, PLLC

(57) **CLAIM**

The ornamental design for a heat sink for memory modules, as shown and described.

**DESCRIPTION**

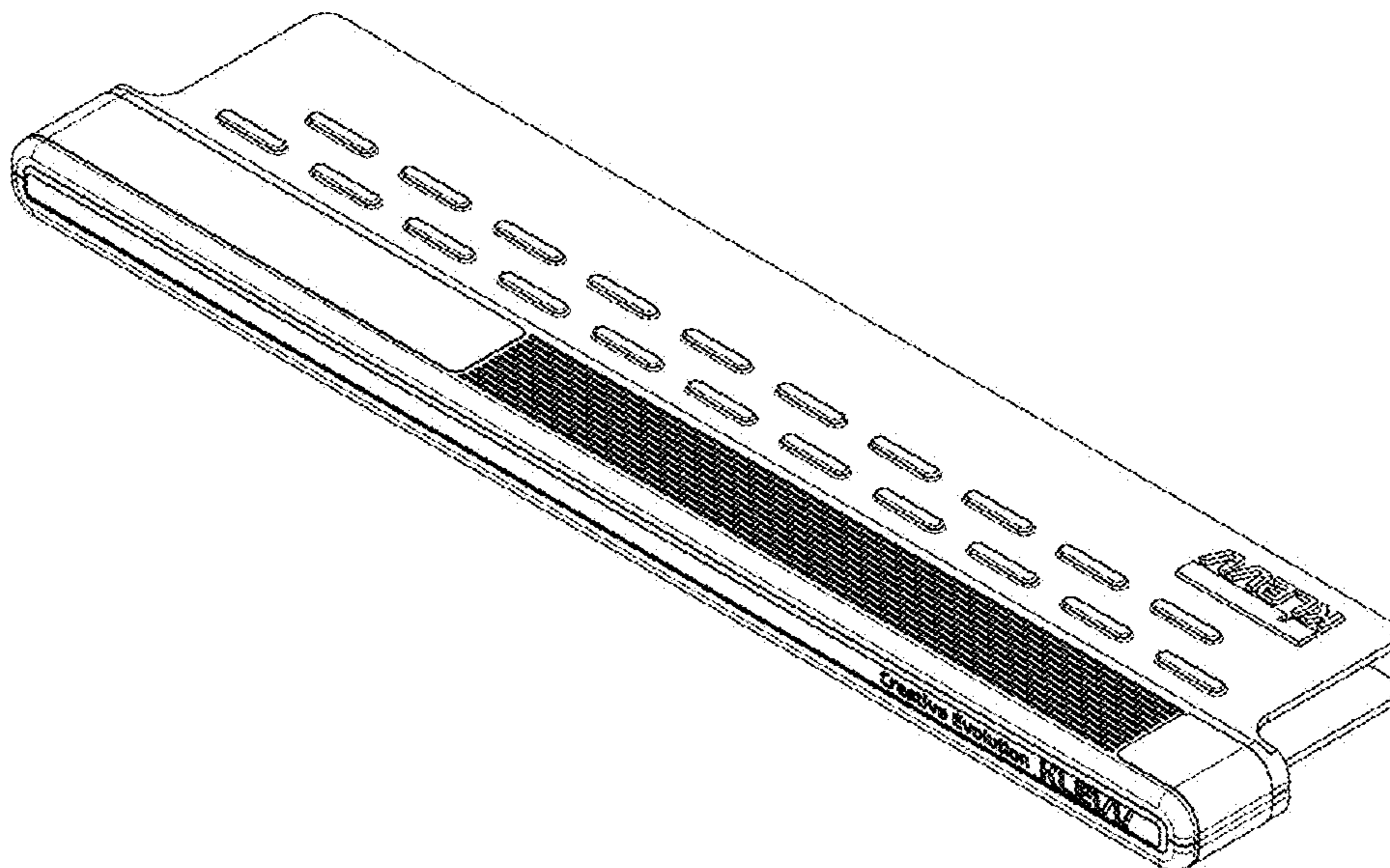
FIG. 1 is a top, front perspective view of the heat sink for memory modules;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a left side view thereof;  
FIG. 5 is a right side view thereof;  
FIG. 6 is a top view thereof; and,  
FIG. 7 is a bottom view thereof.

**1 Claim, 5 Drawing Sheets**

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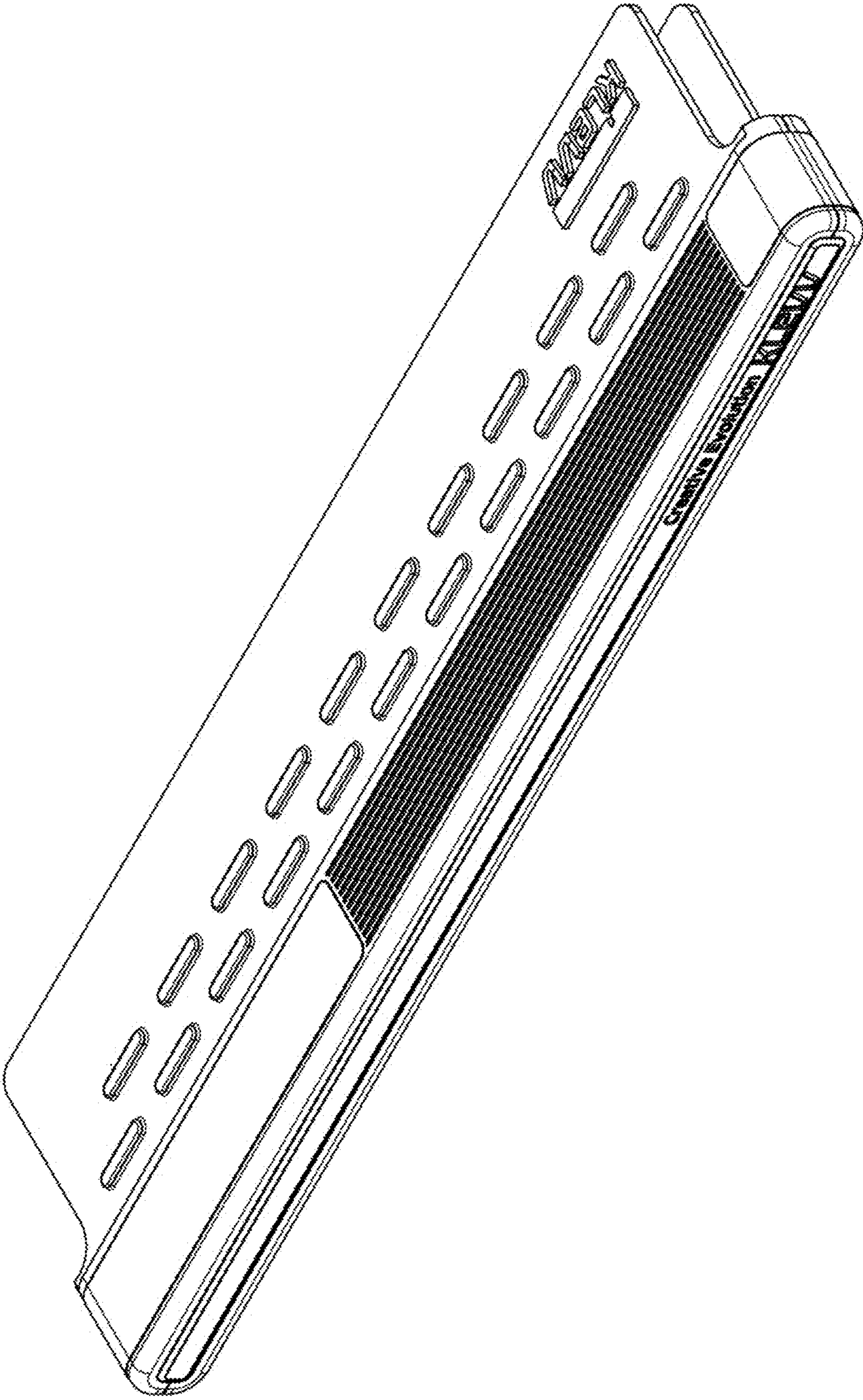


FIG. 1



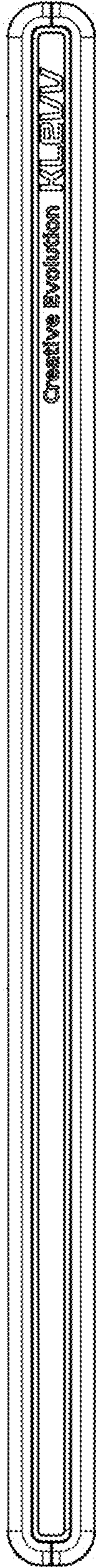


FIG. 2

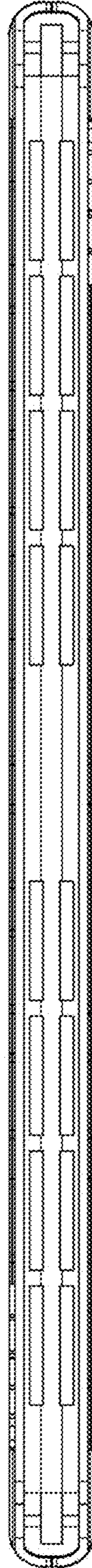


FIG. 3

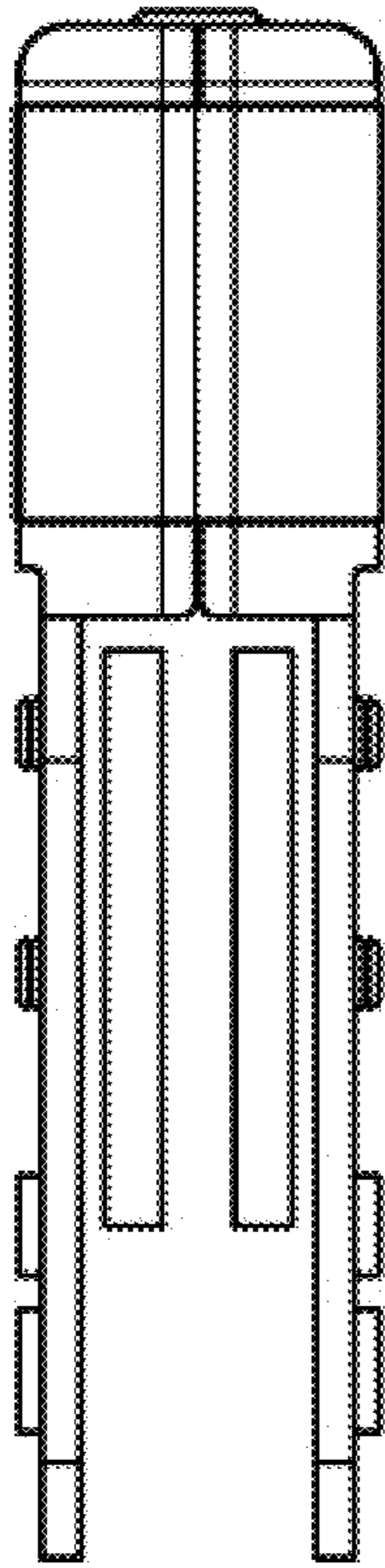


FIG. 4

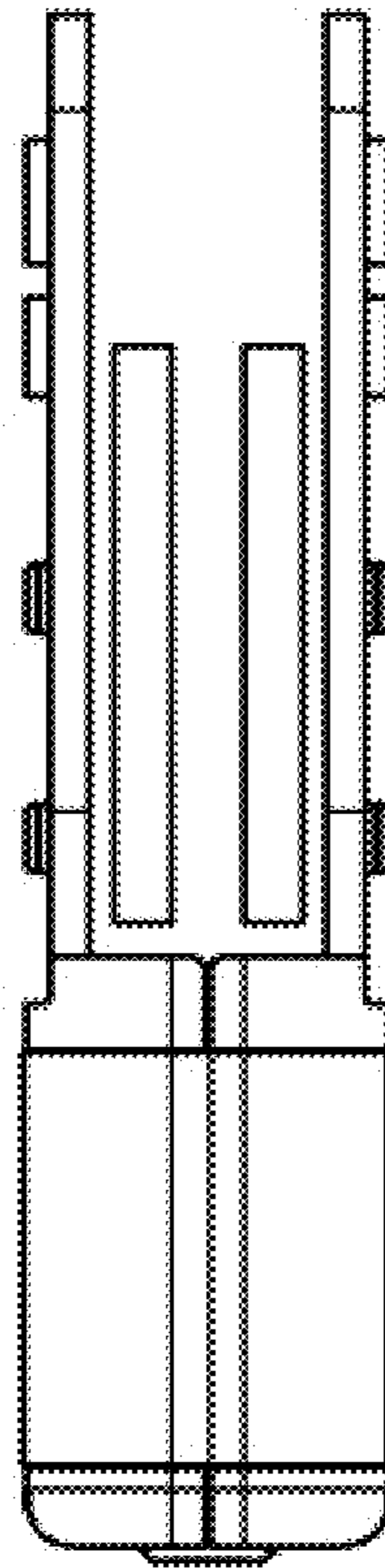


FIG. 5

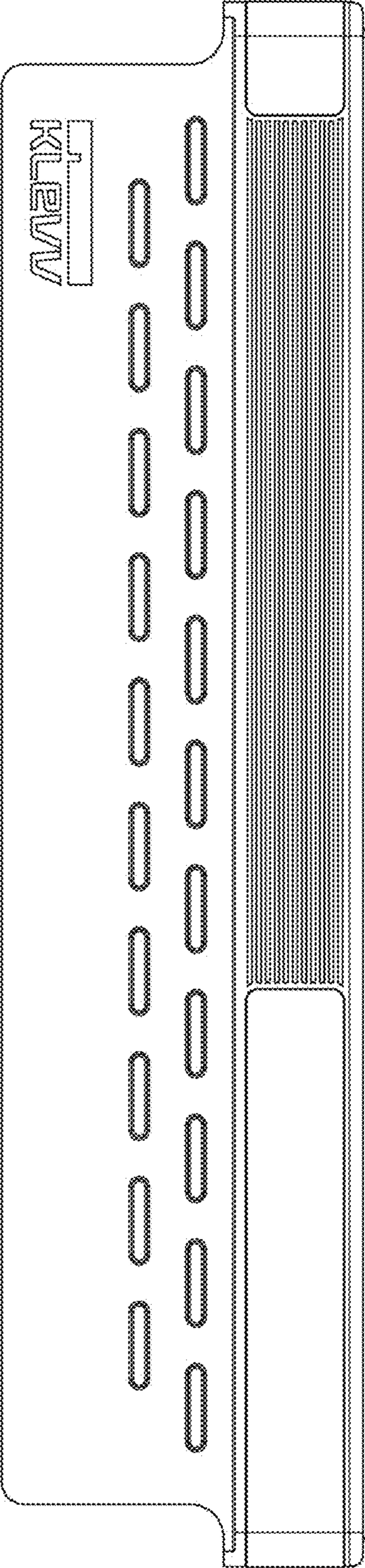


FIG. 6



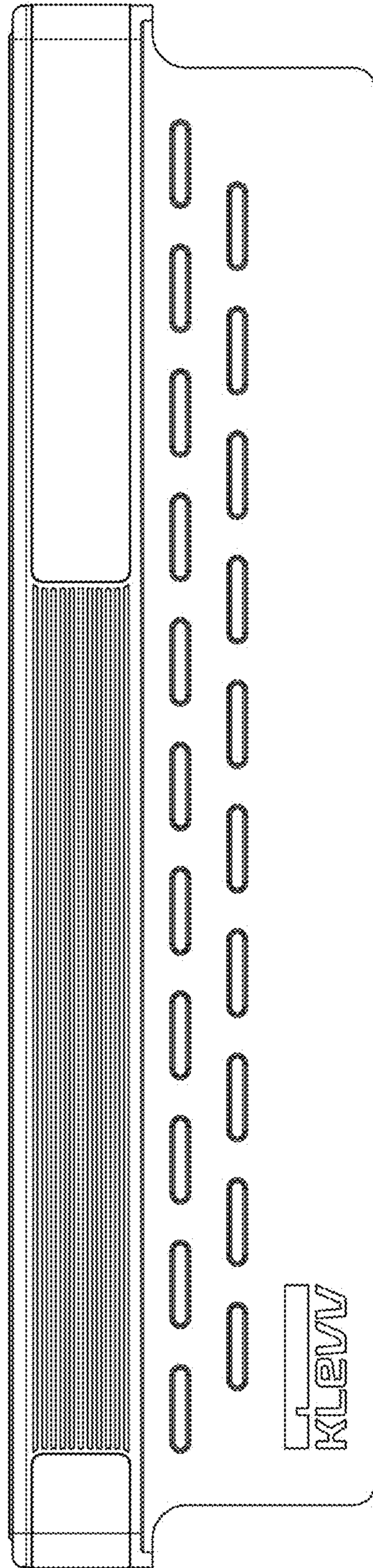


FIG. 7